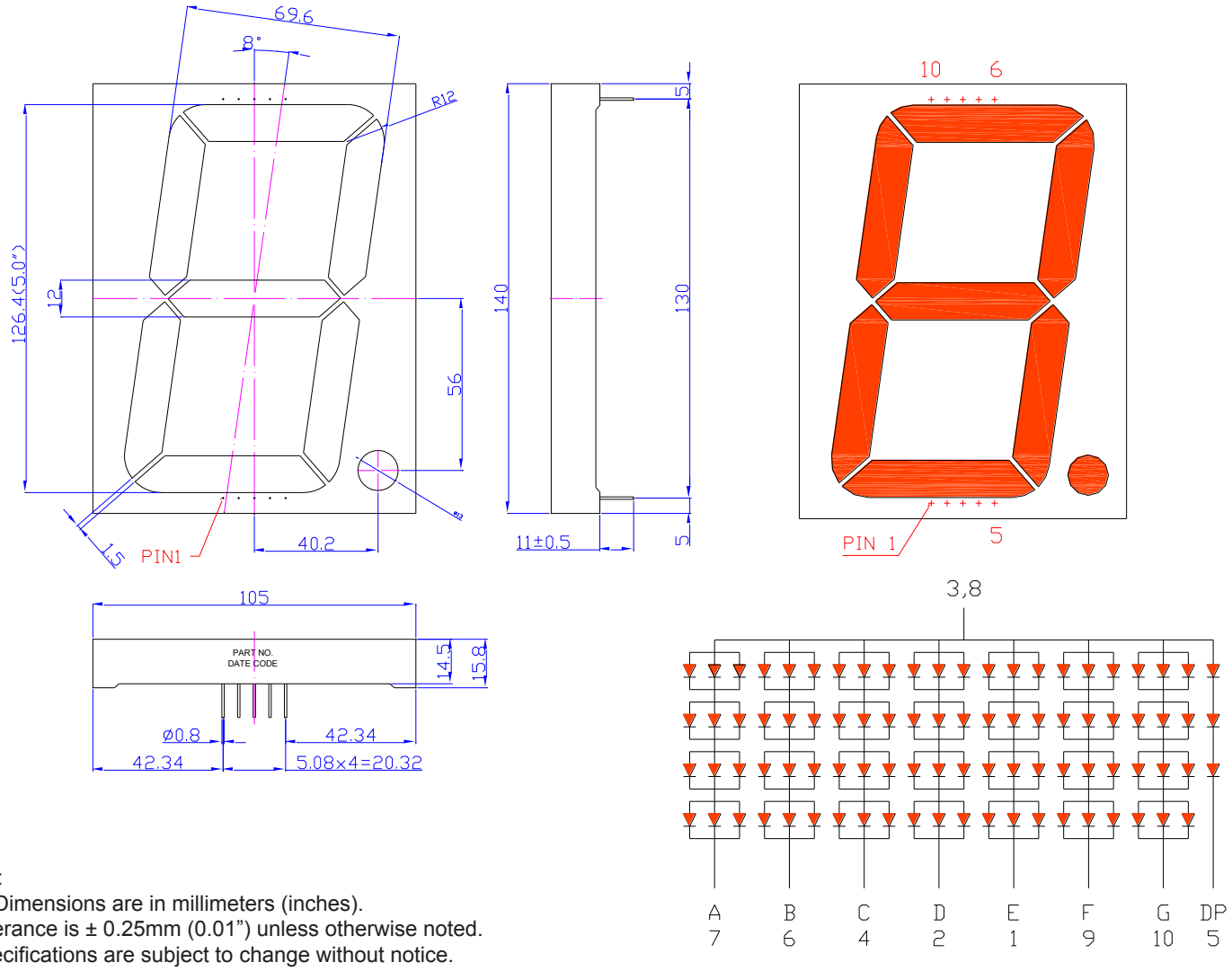
SPECIFICATIONS CDSA500R2W

OUTLINES DIMENSIONS



Notes:
1. All Dimensions are in millimeters (inches).
2. Tolerance is ± 0.25mm (0.01") unless otherwise noted.
3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission	Lens Type	Description
CDSA500R2W	InGaAlP	Red	White Segment	Common Anode

RoHS Compliant Lead Free

ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

ABSOLUTE MAXIMUM RATINGS (TA=25°C)

Parameter	Symbol	Max Rating	Unit
Power Dissipation	P_D	840	mW
Pulse Current Forward Current	I_{FP}	240	mA
Continuous Forward Current	I_F	75	mA
Reverse Voltage	V_R	20	V
Operating Temperature Range	T_{OPR}	-25~+85	°C
Storage Temperature Range	T_{STG}	-25~+85	°C
I_{FP} = Pulse Width ≤ 10 ms, Duty Ratio ≤1/10. Soldering Condition: 260 °C/ 5sec			

OPTICAL-ELECTRICAL CHARACTERISTICS (TA=25°C)

Parameter	Symbol	Test Condition	Value			Unit
			Min	Typ	Max	
Luminous Intensity	I_V	I_F = 30mA	-	450	-	mcd
Forward Voltage per Segment	V_F	I_F = 60mA	-	8	9.6	V
Reverse Current per Segment	I_R	V_R = 20V	-	-	10	μA
Dominant Wavelength	λ_D	I_F = 60mA	-	625	-	nm
Spectral Line half-width	$\Delta\lambda$	I_F = 60mA	-	20	-	nm

RoHS Compliant Lead Free

ChromeLED Corp. reserves the right to make changes at any time in order to supply the best product possible. The most current version of this document will always be available at: www.chromeled.com

OPTICAL CHARACTERISTIC CURVES

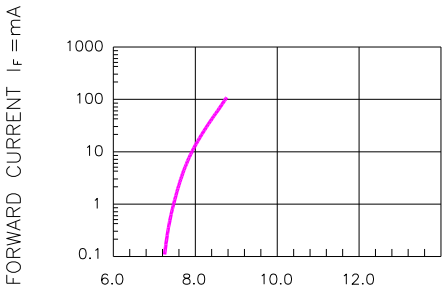


Fig.1 FORWARD CURRENT VS. FORWARD VOLTAGE

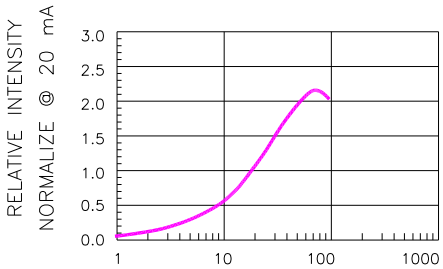


Fig.2 RELATIVE INTENSITY VS. FORWARD CURRENT

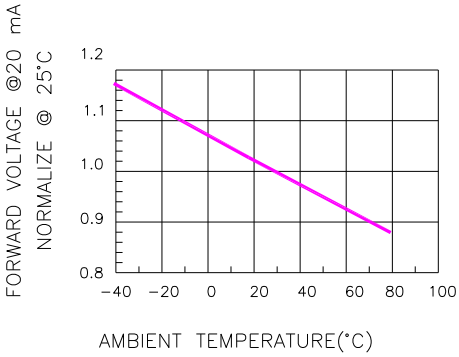


Fig.3 FORWARD VOLTAGE VS. TEMPERATURE

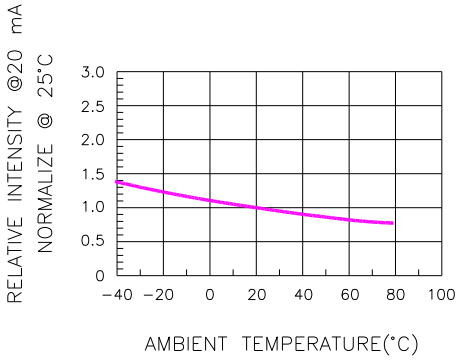


Fig.4 RELATIVE INTENSITY VS. TEMPERATURE

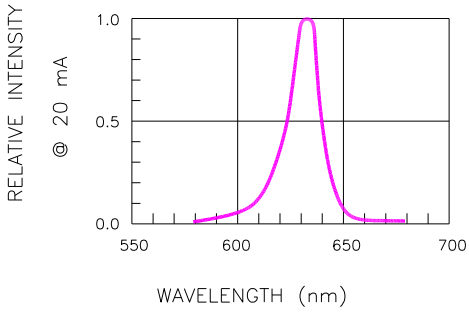


Fig.5 RELATIVE INTENSITY VS. WAVELENGTH

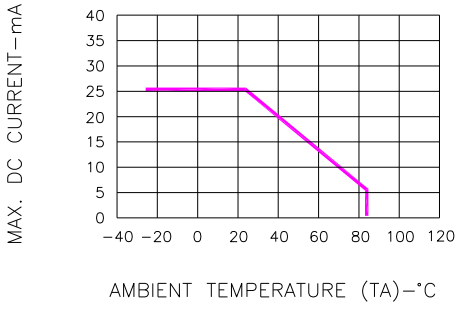


Fig.6 MAX. ALLOWABLE DC CURRENT VS. AMBIENT TEMPERATURE

SOLDERING CONDITIONS – LAMP TYPE LED

* Solder the LED no closer than 3mm from the base of the epoxy bulb. Soldering beyond the base of the tie bar is recommended.

* Recommended soldering conditions

Dip Soldering	
Pre-Heat	100 ˚C Max
Pre-Heat Time	60 Second Max
Solder Bath Temperature	260 ˚C Max
Dippng Time	5 Second Max
Dipping Position	No lower than 3mm from the base of the epoxy

Hand Soldering		
	3mm Series	Others
Temperature Soldering Time Position	300 ˚C Max 3 Second Max No closer than 3mm from the base of the epoxy	350 ˚C Max 3 Second Max No closer than 3mm from the base of the epoxy

* Do not apply any stress to the lead. Particularly when heated.

* The LED must not be repositioned after soldering.

* After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.

* Direct soldering onto a PC board should be avoided. Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the leadframes. When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the user will assume responsibility for any problems. Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur. LEDs should not be soldered directly to double sided PC boards because the heat will deteriorate the epoxy resin.

* When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.

* Cut the LED leadframes at room temperature. Cutting the leadframes at high temperature may cause LED failure.